

深圳市康华尔电子有限公司

SHENZHEN KONUAER ELECTRONICS CO.,LTD

樣品承認書

SAMPLE APPROVAL SHEET

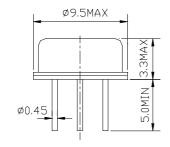
	CUST	OMER:			_				
	SIZE UP:		声表面谐振器		-				
	Volume:		R433.92M		-				
NUMBER:		BER:	TO-39-DIP		_				
DATE:					-				
承認後請寄回一份 PLS SEND BACK ONE COPY TO US AFTER YOUR APPROVAL									
承認結果 CONCLUSION	客戶簽名 SIGNATURE	客戶承認章 STAMP	臣 DA		備注 REMARK				
合格 ACCEPT	SIGIVITURE	STANT		IL	KEMIKK				
不合格 REJECT									
制表: JACK LIU/			审核:						
	<u> </u>								

電話: 27838351

http://www.konuaer.com

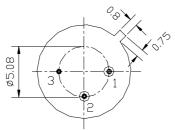
1. Package Dimension (TO-39/3A)

KON R433.92 Unit: mm



Pin No. Function

- 1. Input
- 2. Output
- 3. Ground

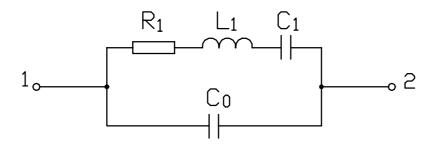


2. Marking

KON R433.92

- 1. Color: Black or Blue
- 2. D: Manufacture's logo
- 3. R1: One-port SAW Resonator
- 4. 433.92: Center Frequency (MHz)

3. Equivalent LC Model



4. Performance

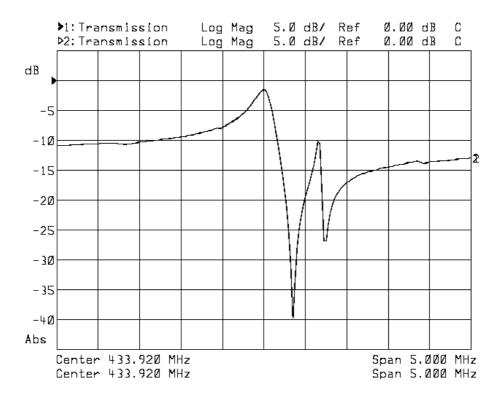
4.1 Maximum Rating

DC Voltage V _{DC}	10V		
AC Voltage V _{PP}	10V (50Hz/60Hz)		
Operation Temperature	-40°C to +85°C		
Storage Temperature	-45℃ to +85℃		
RF Power Dissipation	0dBm		

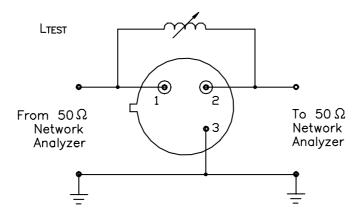
4.2 Electronic Characteristics

Item		Units	Minimum	Typical	Maximum
Center Frequency		MHz	433.845	433.920	433.995
Insertion Loss		dB	_	1.2	2.5
Quality Factor	Unloaded Q		_	11,000	_
	50 Ω Loaded Q			2,000	
Temperature	Turnover Temperature	$^{\circ}$	_	25	
Stability	Turnover Frequency	KHz		fo	
	Freq. Temp. Coefficient	ppm/°C²	_	0.032	
Frequency Aging		ppm/yr	_	< <u>±</u> 10	
DC Insulation Resistance		ΜΩ	1.0	_	_
	Motional Resistance R ₁	Ω	_	18	26
RF Equivalent	Motional Inductance L ₁	μН	_	86	
RLC Model	Motional Capacitance C ₁	fF	_	1.56	_
	Shunt Static Capacitance Co	pF	1.7	2.0	2.3

4.3 Frequency Characteristics



4.4 Test Circuit



Note: Reference temperature shall be $25\pm2^{\circ}\mathbb{C}$. However, the measurement may be carried out at $5^{\circ}\mathbb{C}$ to $35^{\circ}\mathbb{C}$ unless there is a dispute.

5. Reliability

- 5.1 Mechanical Shock: The components shall remain within the electrical specifications after 1000 shocks, acceleration 392 m/s², duration 6 milliseconds.
- 5.2 Vibration Fatigue: The components shall remain within the electrical specifications after loaded vibration at 20 Hz, amplitude 1.5 mm, for 2 hours.
- 5.3 Terminal Strength: The components shall remain within the electrical specifications after pulled 2 kgs weight for 10 seconds towards an axis of each terminal.
- 5.4 High Temperature Storage: The components shall remain within the electrical specifications after being kept at the $85^{\circ}\text{C} \pm 2^{\circ}\text{C}$ for 48 hours, then kept at room temperature for 2 hours.
- 5.5 Low Temperature Storage: The components shall remain within the electrical specifications after being kept at the $-25^{\circ}\text{C} \pm 2^{\circ}\text{C}$ for 48 hours, then kept at room temperature for 2 hours.
- 5.6 Temperature Cycle: The components shall remain within the electrical specifications after 5 cycles of high and low temperature testing (one cycle: 80° C for 30 minutes \rightarrow 25°C for 5 minutes \rightarrow -25°C for 30 minutes)than kept at room temperature for 2 hours.
- 5.7 Humidity Test: The components shall remain within the electrical specifications after being kept at the condition of ambient temperature $40\pm2^{\circ}$ C, and $90\sim95\%$ RH for 48 hours, then kept at room temperature and normal humidity for 2 hours.
- 5.8 Solder-heat Resistance: The components shall remain within the electrical specifications after dipped in the solder at 260° C for 10 ± 1 seconds, then kept at room temperature for 2 hours. (Terminal must be dipped leaving 1.5 mm from the case).
- 5.9 Solderability: Solderability of terminal shall be kept at more than 80% after dipped in the solder flux at $230^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 5 ± 1 seconds.

6. Remarks

6.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning.

6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.